

# TLV320AIC3109EVM-K

This user's guide describes the characteristics, operation, and use of the TLV320AlC3109EVM, both by itself and as part of the TLV320AlC3109EVM-K. This evaluation module (EVM) is a complete mono audio codec with several inputs and outputs, extensive audio routing, mixing, and effects capabilities. A complete circuit description, schematic diagram, and bill of materials (BOM) are also included.

The following related documents are available through the Texas Instruments Web site at www.ti.com.

## Table 1. EVM-Compatible Device Data Sheets

Device	Literature Number
TLV320AIC3109-Q1	SLASE93
TPS73533-Q1	SBVS252
TAS1020B	SLES025

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www.ti.com EVM Overview

#### 1 EVM Overview

#### 1.1 Features

This EVM supports the following features:

- Complete development kit for the evaluation of the TLV320AlC3109-Q1 mono audio codec.
- Connection points are available for line inputs and outputs, external microphone, and mono headphone.
- Onboard microphone for ADC evaluation.
- Direct access to digital audio signals and control interface is provided for simple system integration.
- USB connection to PC provides power, control, and streaming audio data for easy evaluation.

#### 1.2 Introduction

The TLV320AlC3109EVM-K is a complete evaluation and demonstration kit, which includes the TLV320AlC3109EVM and a USB-based motherboard called the USB-MODEVM Interface board. The TLV320AlC3109EVM-K is operational with one USB cable connection to a personal computer. The USB connection provides power, control, and streaming audio data to the EVM kit for reduced setup and configuration. The EVM kit also provides connection points for control signals, audio data, and power for advanced operation, which allows prototyping and connection to the end-user system evaluation. The TLV320AlC3109EVM-K is controlled and configured with the TLV320AlC310xEVM-K Graphical User Interface (GUI) Software, compatible with Microsoft® Windows® operating systems.

#### 1.2.1 TLV320AIC3109EVM-K Block Diagram

The TLV320AlC3109EVM consists of two separate circuit boards, the USB-MODEVM and the TLV320AlC3109EVM. The USB-MODEVM is built around a TAS1020B streaming audio USB controller with an 8051-based core.

The USB-MODEVM has two EVM positions that allow for the connection of two small evaluation modules or one larger evaluation module. The TLV320AlC3109EVM is designed to fit over both of the smaller evaluation module slots as shown in Figure 1.

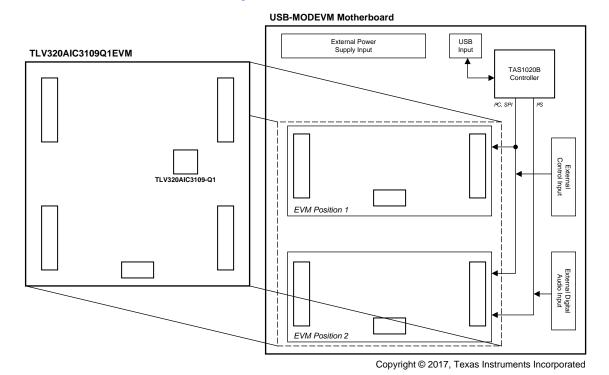


Figure 1. TLV320AIC3109EVM Block Diagram



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#### 1.2.1.1 TLV320AIC3109EVM

The TLV320AlC3109EVM showcases the latest Texas Instruments (TI) mono audio codec, the TLV320AlC3109-Q1 (U3). The TLV320AlC3109-Q1 device is a low-power mono audio codec with a mono headphone amplifier and multiple input and output channels that are programmable in single-ended or fully differential configurations.

The EVM offers different test points, terminals and headers used to evaluate, test and configure the TLV320AlC3109 audio codec in the board. The layout of the board separates analog and digital sections all layers; the analog input and outputs, and analog power supply regulator are located in the left side of the board, while the right side of the board has all the digital signals, like the I²C lines, digital audio signals and onboard EEPROM. Ground planes for both analog and digital grounds are separated, but two common connection points are available through headers J28 and J29. The EVM was designed following the layout recommendations from TLV320AlC3109-Q1 Automotive, Low-Power, 96-kHz, Mono Audio Codec. Several connectors at the edge of the board provide access to the different inputs and outputs of the device. Options to evaluate special features, such as capless headphone configuration and internal mic bias generation are also available. Power, digital audio data, and digital connection for the configuration and control of the device is provided by the USB-MODEVM board. The Figure 2 shows the TLV320AlC3109EVM board.

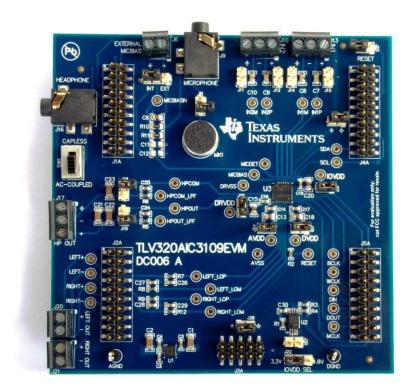


Figure 2. TLV320AIC3109EVM Board



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#### 1.2.1.2 USB-MODEVM Interface Board

The USB-MODEVM board is a motherboard used to configure, control, and provide an interface between a computer and evaluation modules with TI modular EVM form factor. The simple diagram shown in Figure 1 shows only the basic features of the USB-MODEVM Interface board. The USB-MODEVM Interface board is intended to be used in USB mode, where control of the installed EVM is accomplished using the onboard USB controller device, the TAS1020B. Provision is made, however, for driving all the data buses (I²C, SPI<sup>TM</sup>, I²S/AC97) externally. The source of these signals is controlled by SW2 on the USB-MODEVM. Refer to Table 3 for details on the switch settings.

Because the TLV320AlC3109EVM is a double-wide modular EVM, it is installed with connections to both EVM positions, which connects the TLV320AlC3109-Q1 digital interface to the I<sup>2</sup>C control port and audio interface of the TAS1020B.

In the factory configuration, the board is ready to use with the TLV320AlC3109EVM. To view all the functions and configuration options available on the USB-MODEVM board, see the USB-MODEVM Interface Board schematic in Appendix E.

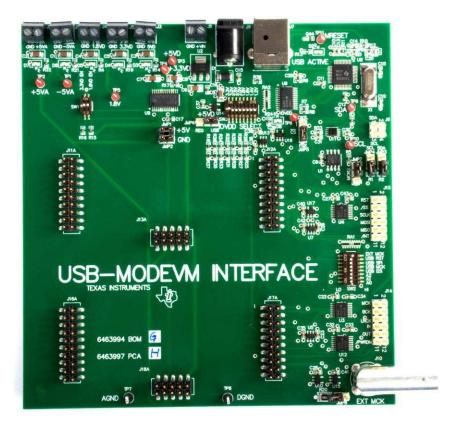


Figure 3. USB-MODEVM Board



# 2 EVM Description and Basics

This section provides information on the analog input and output, digital control, power and general connection of the TLV320AlC3109EVM-K.

# 2.1 Default Configuration and Connections

## 2.1.1 TLV320AIC3109EVM Default Connections

Table 2 provides a list of jumpers found on the EVM and their factory default conditions.

**Table 2. List of Jumpers** 

Jumper	Default Position	Jumper Description	
J7	2-3	Mic bias selection: when connecting 2-3, mic bias comes from the MICBIAS pin on the device; when connecting 1-2, mic bias is supplied from an external power source connected to J6	
J8	Open	Connects onboard Mic to IN1P	
J11	Open	When installed, shorts across the input AC coupling capacitor on IN2M, for DC measuring purposes only	
J12	Open	When installed, shorts across the input AC coupling capacitor on IN2P, for DC measuring purposes only	
J14	Open	When installed, shorts across the input AC coupling capacitor on IN1M, for DC measuring purposes only	
J15	Open	When installed, shorts across the input AC coupling capacitor on IN1P, for DC measuring purposes only	
J18	Open	When installed, shorts across the output capacitor on HPCOM; remove this jumper if using AC-coupled output drive	
J19	Open	When installed, shorts across the output capacitor on HPOUT; remove this jumper if using AC-coupled output drive	
J22	2-3	IOVDD selection: when connecting 2-3, IOVDD is set to +3.3 VD; when connecting 1-2, IOVDD and DVDD are shorted at +1.8 VD	
J23	Open	When installed, allows the USB-MODEVM to hardware reset the device under user control	
J24	Installed	Provides a measuring point for AVDD current	
J25	Installed	Provides a measuring point for DRVDD current	
J26	Installed	Provides a measuring point for DVDD current	
J27	Installed	Provides a measuring point for IOVDD current	
J28	Installed	Connects analog and digital grounds on the lower part the board	
J29	Installed	Connects analog and digital grounds on the upper part the board	
J30	Open	Selects onboard EEPROM as firmware source	



## 2.1.2 USB-MODEVM Default Setting

Table 3 provides a list of the SW2 settings on the USB=MODEVM. For use with the TLV320AlC3109EVM, set SW-2 positions 1 through 7 to ON, and set SW-2.8 to OFF.

Table 3. USB-MODEVM SW2 Settings

SW-2 Switch Number	Label	Switch Description	
1	A0	USB-MODEVM EEPROM I <sup>2</sup> C Address A0 ON: A0 = 0 OFF: A0 = 1	
2	A1	USB-MODEVM EEPROM I <sup>2</sup> C Address A1 ON: A1 = 0 OFF: A1 = 1	
3	A2	USB-MODEVM EEPROM I <sup>2</sup> C Address A2 ON: A2 = 0 OFF: A2 = 1	
4	USB I <sup>2</sup> S	I <sup>2</sup> S Bus Source Selection ON: I <sup>2</sup> S Bus connects to TAS1020 OFF: I <sup>2</sup> S Bus connects to USB-MODEVM J14	
5	USB MCK	I <sup>2</sup> S Bus MCLK Source Selection ON: MCLK connects to TAS1020 OFF: MCLK connects to USB-MODEVM J14	
6	USB SPI	SPI Bus Source Selection ON: SPI Bus connects to TAS1020 OFF: SPI Bus connects to USB-MODEVM J15	
7	USB RST	RST Source Selection ON: EVM Reset Signal comes from TAS1020 OFF: EVM Reset Signal comes from USB-MODEVM J15	
8	EXT MCK	External MCLK Selection ON: MCLK Signal is provided from USB-MODEVM J10 OFF: MCLK Signal comes from either selection of SW2-5	

Table 4 provides a list of USB-MODEVM jumpers found on the EVM.

**Table 4. USB-MODEVM Jumpers** 

Jumper	Default Position	Jumper Description	
JMP1	Installed	Connects analog and digital +5-V supplies	
JMP2	Open	Connects analog and digital grounds	
JMP3	Open	Connects I2C SDA pullup to IOVDD	
JMP4	Open	Connects I2C SCL pullup to IOVDD	
JMP5	2-3	When connecting 2-3, \$\overline{SS}\$ comes from FSX; when connecting 1-2, \$\overline{SS}\$ comes from CNTL	
JMP6	1-2	When connecting 1-2, +5 VD comes from USB; when connecting 2-3, +5 VD comes from U2	
JMP7	1-2	When connecting 1-2, MCLKI comes from USB; when connecting 2-3, MCLKI comes from AVSS and DVSS	
JMP8	Open	Connects resistor across EXT MCLK	



# 2.2 Analog Signals

## 2.2.1 Analog Inputs

The analog inputs to the EVM can be connected through two different methods. The analog input sources can be applied directly to J1 (top or bottom side) or through the analog headers (J10, J13, and J9) around the edge of the board. The connection details of each header and connector are found in Appendix A.

The TLV320AlC3109EVM provides a header in parallel with the input capacitors of each one of the IN1 and IN2 inputs; these headers are provided so end-user can configure the device for DC measurement. Refer to TLV320AlC3109-Q1 Automotive, Low-Power, 96-kHz, Mono Audio Codec for details on the line input specifications.

In addition to the IN1 and IN2 line input connectors, the EVM features an onboard microphone and a mono jack for an external microphone, both connected to IN1P input. When the onboard microphone is used, header J8 must be shorted and J9 should not be connected. Similarly, when external mic is used, J8 should be disconnected. Both microphones are biased to the MICBIASIN bias signal, that can be selected with header J7 from either internal mic bias of the audio codec or an external source connected to J6. Details about the location of the analog inputs of the TLV320AIC3109EVM are shown in Figure 4.

## 2.2.2 Analog Output

The analog outputs to the EVM can be connected through two different methods. The analog outputs are available from the J1 and J2 (top or bottom) or they may be accessed through J16, J17, J20, and J21 at the edges of the board. The connection details can be found in Appendix A.

The line outputs of the TLV320AlC3109-Q1 include the recommended low pass filter to remove the out-of-band noise that can affect the performance of the receiver device. The headphone output of the EVM includes a low pas filter used for test equipment measurement, available in HPCOM\_LPF and HPOUT\_LPF test points. Headers J18 and J19 are used to bypass the AC-coupling capacitors of the headphone output so the headphone output terminal can be used in Capless mode. In addition to the headphone output terminal, a mono jack connector (J16) is included to connect a mono headphone with a typical 3.5mm connector. This jack can be configured to support either AC-Couple or Capless mode by changing the position of switch SW1. The selection on the headphone output mode should match with the configuration of the audio codec. Refer to section Section 4.9 for more details on the headphone output mode configuration. The analog output section of the EVM is shown in Figure 4.



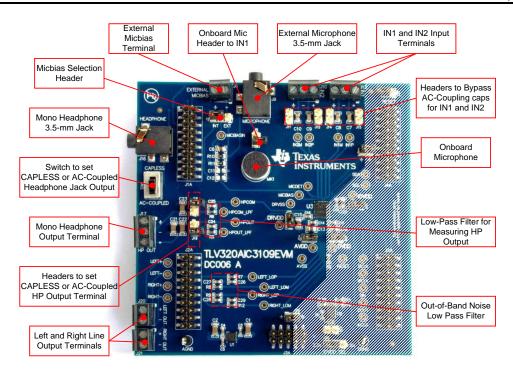


Figure 4. Analog Section of the TLV320AIC3109EVM



## 2.3 Digital Signals

## 2.3.1 Digital Inputs and Outputs

The digital inputs and outputs of the EVM can be monitored through J4 and J5. If external signals need to be connected to the EVM, digital inputs should be connected via J14 and J15 on the USB-MODEVM and the SW2 in the motherboard switch should be changed accordingly (see Section 2.1.2). The connector details are available in Section A.2.

The EVM features test points to directly measure the digital audio signals coming from the USB-MODEVM board. Additionally, test points are provided to monitor the I<sup>2</sup>C control signals. A header to connect the RESET pin of the codec with hardware reset signal from the motherboard is provided. This is useful so the user can perform a hardware reset for the audio codec from the GUI without any board modification. The digital section of the TLV320AIC3109EVM is shown in Figure 5.

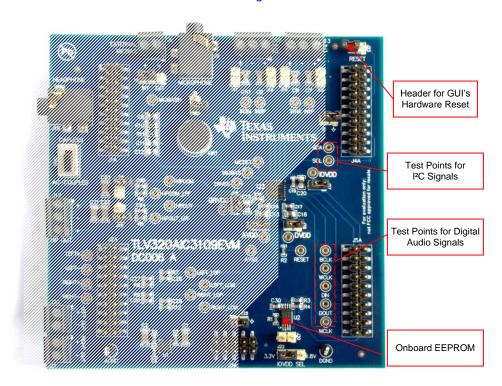


Figure 5. Digital Section of the TLV320AIC3109EVM

#### 2.4 Power Connections

The TLV320AIC3109EVM requires three power supplies to fully evaluate the audio codec:

- +5-V power supply, required to generate +3.3-V supply from the integrated low-dropout voltage regulator (U1) to feed analog power supplies of the codec (AVDD and DRVDD).
- +1.8-V power supply, required to feed the digital core voltage supply (DVDD) and digital input and output voltage supply (IOVDD) of the codec. The selection for the digital input and output voltage (IOVDD) is made via IOVDD SEL header (J22).
- +3.3-V power supply, required for digital input and output voltage supply (IOVDD) of the codec.

The EVM can be powered by external power supplies when being used in stand-alone operation or by the USB-MODEVM when it is plugged onto the motherboard. The following sections discuss each operation mode.



#### 2.4.1 Stand-Alone Operation

When used as a stand-alone EVM, power is applied to J3 directly, making sure to reference the supplies to the appropriate grounds on that connector. The diagram for the power supplies required for stand-alone operation mode are shown in Figure 6.

#### **CAUTION**

Verify that all power supplies are within the safe operating limits shown in *TLV320AlC3109-Q1 Automotive*, *Low-Power*, *96-kHz*, *Mono Audio Codec* before applying power to the EVM.

J3 provides connection to the common power bus for the TLV320AlC3109EVM. Power is supplied on the pins listed in Table 9.

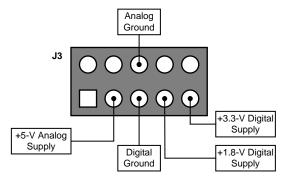


Figure 6. Power Supplies for Stand-Alone Operation

## 2.4.2 USB-MODEVM Operation

The USB-MODEVM Interface board can be powered from several different sources:

- USB
- 6-Vdc to 10-Vdc AC/DC external wall supply (not included)
- Lab power supply

When powered from the USB connection, JMP6 should have a shunt from pins 1–2 (this is the default factory configuration). When powered from 6-V to 10-Vdc, either through the J8 terminal block or J9 barrel jack, JMP6 should have a shunt installed on pins 2–3. If power is applied in any of these ways, onboard regulators generate the required supply voltages and no further power supplies are necessary.

If laboratory supplies are used to provide the individual voltages required by the USB-MODEVM Interface, JMP6 should have no shunt installed. Voltages are then applied to J2 (+5 VA), J3 (+5 VD), J4 (+1.8 VD), and J5 (+3.3 VD). The +1.8 VD and +3.3 VD can also be generated on the board by the onboard regulators from the +5 VD supply; to enable this configuration, the switches on SW1 need to be set to enable the regulators by placing them in the ON position (lower position, looking at the board with text reading right-side up). If +1.8 VD and +3.3 VD are supplied externally, disable the onboard regulators by placing SW1 switches in the OFF position.

Each power supply voltage has an LED (D1-D7) that lights when the power supplies are active.



#### 3 TLV320AlC3109EVM-K Setup and Installation

The following section provides information on using the TLV320AlC3109EVM-K, including set up, program installation, and program usage.

NOTE: If using the EVM in stand-alone mode, the software should be installed per Section 3.1, but the hardware configuration may be different.

#### 3.1 Software Installation

- 1. Download the latest version of the TLV320AlC310xEVM-K GUI.
- 2. Unzip the installation file by clicking on the self-extracting zip file.
- 3. Install the EVM software by double-clicking the Setup executable and follow the directions. The user may be prompted to restart their computer.
- 4. Install the most up-to-date version of National Instrument's VISA™ drivers.
- 5. For Windows 7 and above operating systems, download and install the USB-MODEVM Windows XP/Vista/7 Drivers.

#### 3.2 **EVM Connections**

- 1. Ensure that the TLV320AlC3109EVM is installed on the USB-MODEVM Interface board, aligning J1, J2, J3, J4, and J5 with the corresponding connectors on the USB-MODEVM.
- 2. Verify that the jumpers and switches are in their default conditions.
- 3. Attach a USB cable from the PC to the USB-MODEVM Interface board. The default configuration will provide power, control signals, and streaming audio via the USB interface from the PC. On the USB-MODEVM, LEDs D3-5 and D7 should light to indicate the power is being supplied from the USB.
- 4. For the first connection, the PC should recognize new hardware and begin an initialization process. The user may be prompted to identify the location of the drivers or allow the PC to automatically search for them. Allow the automatic detection option.
- 5. Once the PC confirms that the hardware is operational, D2 on the USB-MODEVM should light to indicate that the firmware has been loaded and the EVM is ready for use. If the LED is not lit, verify that the drivers were installed by trying to unplug and restart at Step 3. If further problems are found. please refer to the TLV320AIC3xEVM-PDK Series Troubleshooting Guide.

After the TLV320AlC3109EVM software installation is complete, evaluation and development with the TLV320AIC3109EVM-K can begin.



## TLV320AIC3109EVM Software

The TLV320AIC3109-Q1 audio codec is a mono version of the TLV320AIC3104 device, so the configuration and control of the TLV320AlC3109EVM is made using the TLV320AlC3104EVM software. Some features of the TLV320AlC3104EVM GUI will not be available for the TLV320AlC3109EVM, detailed information about these features are included in the following sections. As the GUI is adapted for the TLV320AlC3104 device, the names for the signal and internal channels are not the same in some cases for the TLV320AlC3109. In general, the single channel of the TLV320AlC3109-Q1 corresponds to the left channel of the TLV320AIC3104, being the only exception the single headphone output, that corresponds to the right headphone output of the TLV320AlC3104. Table 5 indicates the relationship between the GUI and TLV320AIC3109-Q1 signal and internal block names.

Table 5. TLV320AlC3109EVM and TLV320AlC3104 GUI Signal Name Relation

Name				
TLV320AIC3104 GUI	TLV320AIC3109EVM			
Left ADC	ADC			
Right ADC	not used			
Left DAC	DAC			
Right DAC	not used			
Left AGC	AGC			
Right AGC	not used			
IN1L/LINE1L	IN1/LINE1			
IN1R/LINE1R	IN2/LINE2			
IN2L/LINE2L	not used			
IN2R/LINE2R	not used			
HPRCOM	HPCOM			
HPROUT	HPOUT			
HPLCOM	not used			
HPLOUT	not used			

TI recommends using only the features mentioned in this user's guide for the evaluation of the TLV320AlC3109-Q1 audio codec; otherwise, the device could present unexpected behavior.

The following section discusses the details and operation of the EVM software.

NOTE: For codec configuration, the TLV320AlC3109-Q1 block diagram located in TLV320AlC3109-Q1 Automotive, Low-Power, 96-kHz, Mono Audio Codec is a good reference to help determine the signal routing.

#### 4.1 Device Selection for Operation With TLV320AIC3109EVM

The software that is installed provides operation for several devices of the TLV320AlC310X family of audio codecs. An initial window should appear that looks like Figure 7. For operation with the TLV320AlC3109EVM, the user should select AlC3104 from the pull-down menu and click Accept. The program will take a few seconds to configure the software for operation before proceeding. A progress bar should appear and show the status of the configuration.





Figure 7. Device Selection Window

Once the device is properly configured, the main window of the TV320AlC310x GUI appears. Figure 8 shows the default screen of the GUI. The sections that are shaded in the following captures of the TLV320AlC3104 GUI are not available for the TLV320AlC3109-Q1 evaluation. TI recommends not changing any of the parameters in these sections, otherwise, the performance and behavior of the device cannot be assured.



Figure 8. Default Software Screen



#### 4.2 Front Page Indicators and Functions

Figure 8 illustrates the main screen of the EVM software. The indicators and buttons located above the tabbed section of the front page are visible regardless of which tab is currently being selected.

NOTE: All the indicators corresponding to unused blocks of the TLV320AlC3109-Q1 should be ignored. Refer to Table 5 for more information about the unused sections.

At the top left of the screen is an Interface indicator. This indicator shows which interface is selected for controlling the TLV320AlC3109-Q1, only I<sup>2</sup>C is available for this device.

To the right of the Interface indicator is a group box called Firmware. This box indicates where the firmware being used is operating from - in this release, the firmware is on the USB-MODEVM, so the user should see USB-MODEVM in the box labeled Located On:. The version of the firmware appears in the Version box below the Located On: box.

To the right, the next group box contains controls for resetting the TLV320AlC3109-Q1. A software reset can be done by writing to a register in the TLV320AlC3109-Q1, and this is accomplished by pushing the button labeled **Software Reset**. The TLV320AlC3109-Q1 also may be reset by toggling a pin on the TLV320AlC3109-Q1, which is done by pushing the **Hardware Reset** button.

#### **CAUTION**

In order to perform a hardware reset, the RESET jumper (JMP19) must be installed and SW2-7 on the USB-MODEVM must be turned OFF. Failure to do either of these steps results in not generating a hardware reset or causing unstable operation of the EVM, which may require cycling power to the USB-MODEVM.

Below the Firmware box, the Device Connected LED should be green when the EVM is connected. If the indicator is red, the EVM is not properly connected to the PC. Disconnect the EVM and verify that the drivers were correctly installed, then reconnect; if it does not work, try restarting the software.

On the upper right portion of the screen, several indicators are located which provide the status of various portions of the TLV320AlC3109-Q1. These indicators are activated by pressing the **Indicator Updates** button below the **Device Connected** LED. These indicators, as well as the other indicators on this panel, are updated only when the front panel of the software is inactive, once every 20 ms.

The ADC Overflow and DAC Overflow indicators light when the overflow flags are set in the TLV320AlC3109-Q1. Below these indicators are the AGC Noise Threshold Exceeded indicators that show when the AGC noise threshold is exceeded. To the far right of the screen, the Short Circuit Detect indicators show when a short-circuit condition is detected, if this feature has been enabled. Below the short-circuit indicators, the AGC Gain Applied indicators use a bar graph to show the amount of gain which has been applied by the AGC, and indicators that light when the AGC is saturated.



## 4.3 Audio Input/ADC Tab

The **Audio Input/ADC** tab allows control of the analog input mixer and the ADC. The controls are displayed to look similar to an audio mixing console, as shown in Figure 9. Each analog input channel has a vertical strip that corresponds to that channel. By default, all inputs are muted when the TLV320AlC3109EVM is powered up.

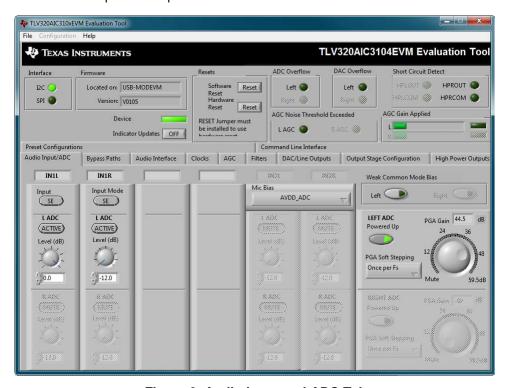


Figure 9. Audio Input and ADC Tab

To route an analog input to the ADC:

- 1. Select the **Input Mode** button to correctly show if the input signal is single-ended (*SE*) or fully-differential (*Diff*). Inputs that are single-ended should be made to the positive signal terminal.
- 2. Click on the button of the analog input channel that corresponds to the correct ADC. The caption of the button should change to *Active*.
- 3. Adjust the **Level** control to the desired attenuation for the connected channel. This level adjustment can be done independently for each connection.

The TLV320AlC3109-Q1 offers a programmable microphone bias that can either be powered down or set to 2 V, 2.5 V, or the power supply voltage of the ADC (AVDD\_ADC). Control of the microphone bias (mic bias) voltage is accomplished by using the **Mic Bias** pull-down menu button above the last two channel strips. To use the onboard microphone, J8 must be installed and nothing should be plugged into J9. In order for the mic bias settings in the software to take effect, J7 should be set to connect positions 2 and 3 (INT), so that mic bias is controlled by the TLV320AlC3109-Q1.

In the upper right portion of this tab are controls for **Weak Common Mode Bias**. Enabling these controls will result in unselected inputs to the ADC to be weakly biased to the ADC common mode voltage.

Below these controls are the controls for the ADC PGA, including the master volume controls for the ADC inputs. The ADC channel can be powered up or down as needed using the **Powered Up** button. PGA soft-stepping for the ADC channel is selected using the pull-down menu control. The large knob sets the actual **ADC PGA Gain** and allows adjustment of the PGA gains from 0 dB to 59.5 dB, in 0.5-dB steps (excluding Mute). At the extreme counterclockwise rotation, the channel is muted. Rotating the knob clockwise increases the PGA gain, which is displayed in the box directly above the volume control.



## 4.4 Bypass Paths

The **Bypass Paths** tab shows the active and passive bypass paths available for control.

The passive analog bypass paths allow the inputs to be routed straight through the device to the outputs without turning on any of the internal circuitry. This provides a signal path through the device with minimal power consumption.

The active bypass paths allow the inputs to bypass the ADC and DAC functional blocks and be routed to the analog output mixers to be summed into the output amplifiers. The **Bypass Paths** tab is shown in Figure 10.



Figure 10. Bypass Paths



#### 4.5 Audio Interface Tab

The **Audio Interface** tab, shown in Figure 11, allows configuration of the audio digital data interface to the TLV320AlC3109-Q1.

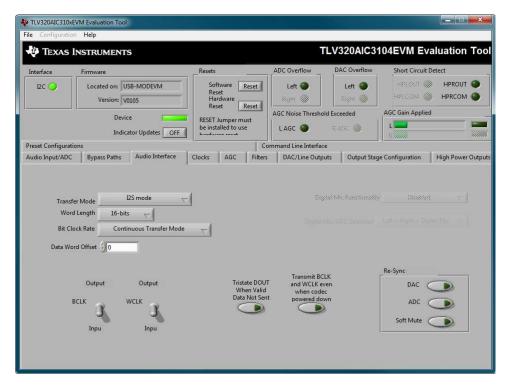


Figure 11. Audio Interface Tab

The interface mode may be selected using the **Transfer Mode** control—selecting either I<sup>2</sup>S mode, DSP mode, or Right- or Left-Justified modes. Word length can be selected using the **Word Length** control, and the bit clock rate can also be selected using the **Bit Clock** rate control. The **Data Word Offset**, used in TDM mode (see *TLV320AIC3109-Q1 Automotive*, *Low-Power*, *96-kHz*, *Mono Audio Codec*) can also be selected on this tab.

Along the bottom of this tab are controls for choosing the **BLCK** and **WCLK** as being either inputs or outputs. With the codec configured in *Slave* mode, both the BCLK and WCLK are set to inputs. If the codec is in *Master* mode, then BCLK and WCLK are configured as outputs. Additionally, two buttons provide the option for placing the DOUT line in a 3-state mode when there is not valid data and transmitting BLCK and WCLK when the codec is powered down.

Re-synchronization of the audio bus is enabled using the controls in the lower right corner of this screen. Re-synchronization is done if the group delay changes by more than ±FS / 4 for the ADC or DAC sample rates (see *TLV320AlC3109-Q1 Automotive*, *Low-Power*, *96-kHz*, *Mono Audio Codec*). The channels can be soft muted when doing the re-sync if the **Soft Mute** button is enabled.

The default mode for the EVM is configured as 44.1 kHz, 16-bit, I<sup>2</sup>S words, and the codec is a slave (BCLK and WCLK are supplied to the codec externally). For use with the PC software and the USB-MODEVM, the default settings should be used; no change to the software is required.



#### 4.6 Clocks Tab

The TLV320AlC3109-Q1 provides a phase-locked loop (PLL) that allows flexibility in the clock generation for the ADC and DAC sample rates. The **Clocks** tab contains the controls used to configure the TLV320AlC3109-Q1 for operation with a wide range of master clocks. See the *Audio Clock Generation Processing* figure in *TLV320AlC3109-Q1 Automotive*, *Low-Power*, *96-kHz*, *Mono Audio Codec* for further details of selecting the correct clock settings.

For use with the PC software and the USB-MODEVM, the clock settings must be set a certain way. If the settings are changed from the default settings which allow operation from the USB-MODEVM clock reference, the EVM settings can be restored automatically by pushing the **Load EVMS Clock Settings** button at the bottom of this tab. Note that changing any of the clock settings from the values loaded when this button is pushed may result in the EVM not working properly with the PC software or USB interface. If an external audio bus is used (audio not driven over the USB bus), then settings may be changed to any valid combination. The **Clocks** tab is shown in Figure 12.

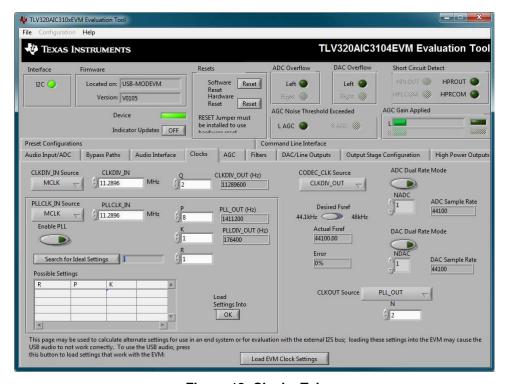


Figure 12. Clocks Tab

#### 4.6.1 Configuring the Codec Clocks and Fsref Calculation

The codec clock source is chosen by the **CODEC\_CLK Source** control. When this control is set to *CLKDIV OUT*, the PLL is not used; when set to *PLLDIV OUT*, the PLL is used to generate the clocks.

NOTE: Per TLV320AlC3109-Q1 Automotive, Low-Power, 96-kHz, Mono Audio Codec, the codec should be configured to allow the value of Fsref to fall between the values of 39 kHz to 53 kHz.



#### 4.6.1.1 Use Without PLL

Setting up the TLV320AlC3109-Q1 for clocking without using the PLL permits the lowest power consumption by the codec. The **CLKDIV\_IN** source can be selected as either *MCLK*, *GPIO2*, or *BCLK*, the default is MCLK. The CLKDIV\_IN frequency is then entered into the **CLKDIV\_IN** box, in megahertz (MHz). The default value shown, 11.2896 MHz, is the frequency used on the USB-MODEVM board. This value is then divided by the value of Q, which can be set from 2 to 17; the resulting *CLKDIV\_OUT* frequency is shown in the indicator next to the **Q** control. The result frequency is shown as the *Actual Fsref*.

#### 4.6.1.2 Use With The PLL

When PLLDIV\_OUT is selected as the codec clock source, the PLL is used. The PLL clock source is chosen using the **PLLCLK\_IN** control, and may be set to either *MCLK*, *GPIO2*, or *BCLK*. The PLLCLK\_IN frequency is then entered into the **PLLCLK\_IN Source** box.

The PLL\_OUT and PLLDIV\_OUT indicators show the resulting PLL output frequencies with the values set for the P, K, and R parameters of the PLL. See TLV320AIC3109-Q1 Automotive, Low-Power, 96-kHz, Mono Audio Codec for an explanation of these parameters. The parameters can be set by clicking on the up or down arrows of the **P**, **K**, and **R** combo boxes, or they can be typed into these boxes.

The values can also be calculated by the PC software. To use the PC software to find the ideal values of P, K, and R for a given PLL input frequency and desired Fsref:

- 1. Verify the correct reference frequency is entered into the **PLLCLK\_IN Source** box in megahertz (MHz).
- 2. The desired Fsref should be set using the **Fsref** switch.
- 3. Push the **Search for Ideal Settings** button. The software will start searching for ideal combinations of P, K, and R which achieve the desired Fsref. The possible settings for these parameters are displayed in the spreadsheet-like table illustrated in Figure 12, labeled *Possible Settings*.
- 4. Click on a row in this table to select the P, K, and R values located in that row. Notice that when this is done, the software updates the P, K, R, PLL\_OUT, and PLLDIV\_OUT readings, as well as the *Actual Fsref* and Error displays. The values show the calculations based on the values that were selected. This process does not actually load the values into the TLV320AlC3109-Q1; however, it only updates the displays in the software. If more than one row exists, the user can choose the other rows to see which of the possible settings comes closest to the ideal settings.

When a suitable combination of P, K, and R have been chosen, pressing the **Load Settings into Device?** button will download these values into the appropriate registers on the TLV320AlC3109-Q1.

## 4.6.1.3 Setting the ADC and DAC Sampling Rates

The Fsref frequency that is determined by either enabling or bypassing the PLL (see Section 4.6.1.1 or Section 4.6.1.2) is used to set the actual ADC and DAC sampling rates. Using the NADC and NDAC factors, the sampling rates are derived from the Fsref. If dual-rate mode is desired, this option can be enabled for either the ADC or DAC by pressing the corresponding Dual Rate Mode button. The ADC and DAC sampling rates are shown in the box to the right of each control.



#### 4.7 AGC Tab

The **AGC** tab consists a set of controls to configure the automatic Gain Control (AGC) of the TLV320AlC3109-Q1. The AGC function is described in *TLV320AlC3109-Q1 Automotive*, *Low-Power*, *96-kHz*, *Mono Audio Codec*. The default **AGC** tab configuration is shown in Figure 13.

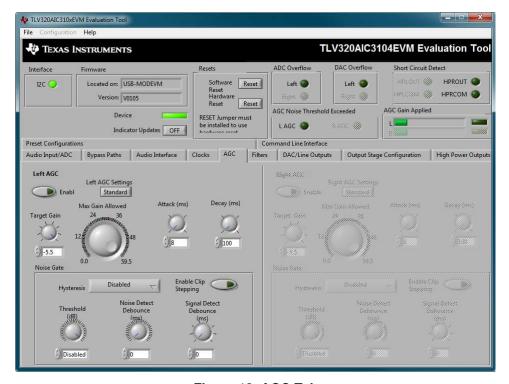


Figure 13. AGC Tab

The AGC can be enabled using the **Enable** button. **Target** gain (dB), **Attack** time (milliseconds), **Decay** time (milliseconds), and the **Maximum PGA Gain Allowed** (dB) can all be set, respectively, using the four corresponding knobs.

The TLV320AlC3109-Q1 allows for the Attack and Decay times of the AGC to be set up in two different modes, standard and advanced. The **AGC Settings** button determines the mode selection. The *Standard* mode provides several preset times that can be selected by adjustments made to the **Attack** and **Decay** knobs. If finer control over the times is required, then the *Advanced* mode should be selected. When the *Advanced* mode is enabled, two tabs should appear that allow separate, advanced control of the Attack and Delay times of the AGC (see Figure 14). These options allow selection of the base time as well as a multiplier to achieve the actual times shown in the corresponding text box. The **Use advanced** button should be enabled to program the registers with the correct values selected via the pull-down options for base time and multiplier.



Figure 14. Advanced AGC settings



Noise gate functions, such as **Hysteresis**, **Enable Clip stepping**, **Threshold (dB)**, **Signal Detect Debounce (ms)**, and **Noise Detect Debounce (ms)** are set using the corresponding controls in the **Noise Gate** group box.

#### 4.8 Filters Tab

The TLV320AlC3109-Q1 has an advanced feature set for applying digital filtering to audio signals. This tab controls all of the filter features of the TLV320AlC3109-Q1. In order to use this tab and have plotting of filter responses correct, the DAC sample rate must be set correctly. Therefore, the clocks must be set up correctly in the software following the discussion in Section 4.6. The **Filters** tab is depicted in Figure 15.

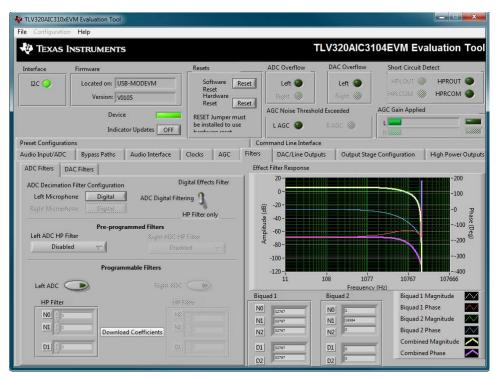


Figure 15. Filters Tab

The AlC3104 digital filtering is available to both the ADC and DAC. The ADC has optional high pass filtering and allows the digital output from the ADC through digital effects filtering before exiting the codec through the PCM interface. Likewise, the digital audio data can be routed through the digital effects filtering before passing through the optional de-emphasis filter before the DAC. The digital effects filtering can only be connected to either the ADC or DAC, not both at the same time.

The Filters tab is divided into several areas. The left side of the tab, is used to select between the DAC or ADC filters and assist in the selection and calculating the desired filter coefficients. The right hand side of the tab shows a frequency response plot of the digital effects filter selected and the coefficients that are programmed into the device. The plots show the magnitude and phase response of each biquad section, plus the combined responses of the two biquad filters. Note that the plot shows only the responses of the effect filters, not the combined response of those filter along with the de-emphasis and ADC high-pass filters.



#### 4.8.1 ADC Filters

## 4.8.1.1 High Pass Filter

The TLV320AlC3109-Q1 ADC provides the option of enabling a high-pass filter, which helps to reduce the effects of DC offsets in the system. The ADC high-pass filter tab is shown in Figure 16. This tab shows the options for programming various filter associated with the ADC. The high-pass filter has two modes: standard and programmable.

The standard high-pass filter option allows the selection of the high-pass filter frequency from several preset options that can be chosen with the **ADC HP Filter** control. Four options are available for this filter setting, one for disable and other three different corner frequencies which are based on the ADC sample rate.

For custom filter requirements, the programmable function allows custom coefficients to achieve a different filter than provided by the preset filters. The controls for the programmable high-pass filter are located under the **Programmable Filters** heading. The process should use the following steps:

- 1. The filter coefficients can be entered in the **HP Filter** controls near the bottom of the tab.
- 2. Press the **Download Coefficients** button to download the coefficients to the codec registers.
- 3. Enable the Programmable High-Pass Filters by selecting the ADC button.

The programmable high-pass filter should now be correctly programmed and enabled. The ADC can now be enabled with the high-pass filter.

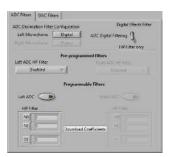


Figure 16. ADC High Pass Filters

#### 4.8.1.2 Digital Effects Filter - ADC

The ADC digital outputs stream can be routed through the digital effects filter in the codec to allow custom audio performance. The digital effects filter cannot operate on both the ADC or DAC at the same time. The digital effects filter operation is discussed in Section 4.8.3.

## 4.8.2 DAC Filters

The **DAC Filters** tab is shown in Figure 17. Detailed information about the different configuration options for the DAC filters is discussed in the following sections.



Figure 17. DAC Filters



#### 4.8.2.1 De-emphasis Filters

The de-emphasis filters used in the TLV320AlC3109-Q1 can be programmed as described in *TLV320AlC3109-Q1 Automotive*, *Low-Power*, *96-kHz*, *Mono Audio Codec*, using this tab. Enter the coefficients for the de-emphasis filter response desired. While on this tab, the de-emphasis response is shown on the *Effect Filter Response* graph; however, note that this response is not included in graphs of other effect responses when on the other filter design tabs.



Figure 18. De-emphasis Filters

## 4.8.2.2 DAC Digital Effects Filter

The digital audio input stream can be routed through the digital effects filter in the codec before routing to the DAC to allow custom audio performance. The digital effects filter cannot operate on both the ADC or DAC at the same time. The digital effects filter operation is discussed in Section 4.8.3.

#### 4.8.3 Digital Effects Filters

The digital effect filters (or biquad filters) of the TLV320AlC3109-Q1 are selected using the check boxes shown in the Figure 17 tab. The De-emphasis filters are described in *TLV320AlC3109-Q1 Automotive*, *Low-Power*, *96-kHz*, *Mono Audio Codec*, and their coefficients may be changed.

When designing filters for use with TLV320AlC3109-Q1, the software allows for several different filter types to be used. These options are shown on a tab control in the lower left corner of the screen. When a filter type is selected, and suitable input parameters defined, the response is shown in the *Effect Filter Response* graph. Regardless of the setting for enabling the Effect Filter, the filter coefficients are not loaded into the TLV320AlC3109-Q1 until the **Download Coefficients** button is pressed. To avoid noise during the update of coefficients, it is recommended for the user to uncheck the **Effect Filter** check box before downloading coefficients. Once the desired coefficients are in the TLV320AlC3109-Q1, enable the filters by checking the **Effect Filters** box again.

#### 4.8.3.1 Shelf Filters

A shelf filter is a simple filter that applies a gain (positive or negative) to frequencies above or below a certain corner frequency. As shown in Figure 19, in *Bass* mode a shelf filter applies a gain to frequencies below the corner frequency; in *Treble* mode the gain is applied to frequencies above the corner frequency.



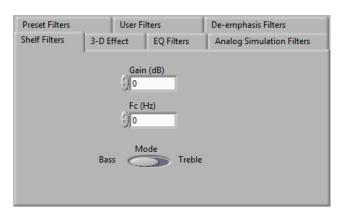


Figure 19. Shelf Filters

To use these filters, enter the gain desired and the corner frequency. Choose the mode to use (*Bass* or *Treble*); the response is plotted on the *Effect Filter Response* graph.

#### 4.8.3.2 EQ Filters

EQ, or parametric filters can be designed on this tab, as shown in Figure 20). Enter a gain, bandwidth, and a center frequency (Fc). Either bandpass (positive gain) or band-reject (negative gain) filters can be created

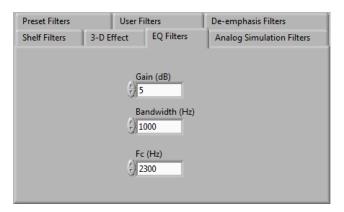


Figure 20. EQ Filters

## 4.8.3.3 Analog Simulation Filters

Biquads are quite good at simulating analog filter designs. For each biquad section on this tab, enter the desired analog filter type to simulate (Butterworth, Chebyshev, Inverse Chebyshev, Elliptic, or Bessel). Parameter entry boxes appropriate to the filter type are shown (ripple, for example, with Chebyshev filters, and so forth). Enter the desired design parameters and the response is shown. The **Analog Simulation Filters** tab is shown in Figure 21.



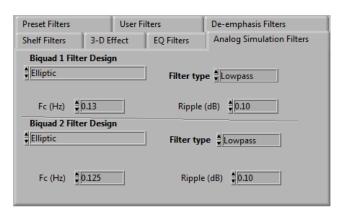


Figure 21. Analog Simulation Filters

#### 4.8.3.4 Preset Filters

Many applications are designed to provide preset filters common for certain types of program material. The **Preset Filters** tab, as shown in Figure 22, allows selection of one of four preset filter responses - Rock, Jazz, Classical, or Pop.

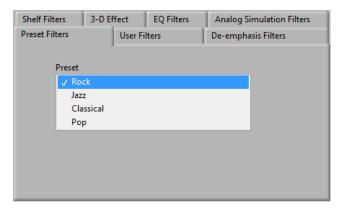


Figure 22. Preset Filters

#### 4.8.3.5 User Filters

If filter coefficients are known, they can be entered directly on this tab for both biquads. The filter response will **not** be shown on the *Effect Filter Response* graph for user filters. The **User Filters** tab is depicted in Figure 23.

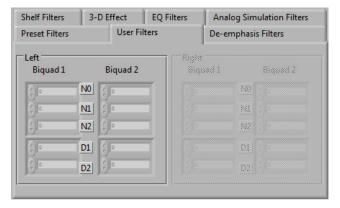


Figure 23. User Filters



#### 4.8.3.6 3-D Effect

The **3-D Effect** is described in *TLV320AlC3109-Q1 Automotive*, *Low-Power*, *96-kHz*, *Mono Audio Codec*. The 3-D effect uses the two biquad sections in a different way than most other effect filter settings. To use this effect properly, make sure the appropriate coefficients are already loaded into the two biquad sections. The **User Filters** tab may be used to load the coefficients. Figure 24 shows the **3-D Effect** tab.

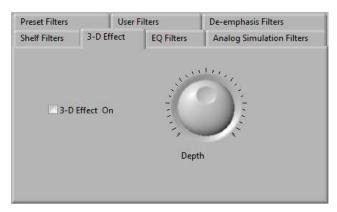


Figure 24. 3D Effect Settings

To enable the 3-D effect, check the **3-D Effect On** box. The **Depth** knob controls the value of the *3-D Attenuation Coefficient*.

## 4.9 Output Stage Configuration Tab

The **Output Stage Configuration** tab (shown in Figure 25) allows the setting of different features of the output drivers.

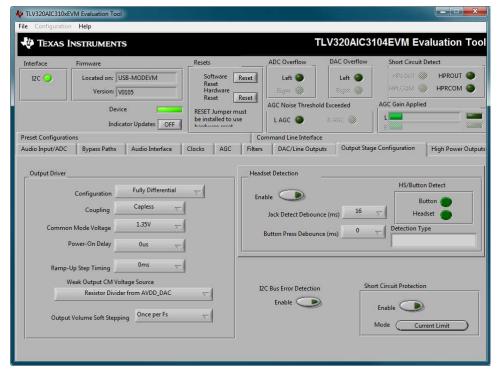


Figure 25. Output Stage Configuration Tab



The **Configuration** control may be set as either *Fully-Differential* or *Pseudo-Differential*. This control is used to determine if the output stage is being used to drive a fully differential output load or a output load where one of the outputs if referenced to a common-mode voltage (pseudo-differential).

The output **Coupling** control can be chosen as either *Capless* or *AC-coupled*. This setting should correspond to the setting of the hardware switch (SW1) on the TLV320AlC3109EVM (*CAPLESS* or *CAP*).

The common mode voltage of the outputs may be set to 1.35 V, 1.5 V, 1.65 V, or 1.8 V using the **Common Mode Voltage** control.

The TLV320AlC3109-Q1 offers several options to help reduce the turnon and turnoff pop of the output amplifiers. The **Power-On Delay** of the output drivers can be set using the corresponding control from 0's up to 4 seconds. **Ramp-Up Step Timing** can also be adjusted from 0ms to 4ms. The outputs can be set to soft-step their volume changes, using the **Output Volume Soft Stepping** control, and set to step once per Fs period, once per two Fs periods, or soft-stepping can be disabled altogether.

The high-power outputs of the TLV320AlC3109-Q1 can be configured to go to a weak common-mode voltage when powered down. The source of this weak common-mode voltage can be set on this tab with the **Weak Output CM Voltage Source** drop-down. Choices for the source are either a resistor divider off the AVDD\_DAC supply, or a bandgap reference. Refer to *TLV320AlC3109-Q1 Automotive*, *Low-Power*, *96-kHz*, *Mono Audio Codec* for more details on this option.

Headset detection features are enabled using the **Enable** button in the **Headset Detection** group box. When enabled, the indicators in the **HS/Button Detect** group box will light when either a button press or headset is detected. When a headset is detected, the type of headset is displayed in the **Detection Type** indicator. Debounce times for detection are set using the **Jack Detect Debounce** and **Button Press Debounce** controls, which offer debounce times in different numbers of milliseconds. Refer to *TLV320AlC3109-Q1 Automotive*, *Low-Power*, *96-kHz*, *Mono Audio Codec* for more information regarding headset detection.

Output short-circuit protection can be enabled in the **Short Circuit Protection** group box. Short Circuit Protection can use a current-limit mode, where the drivers will limit current output if a short-circuit condition is detected, or in a mode where the drivers will power down when such a condition exists.

The  $I^2C$  Bus Error Detection button allows the user to enable circuitry which will set a register bit (Register 107, D0) if an  $I^2C$  bus error is detected.

## 4.10 DAC/Line Outputs Tab

The **DAC/Line Outputs** tab controls the DAC power and volume, as well as routing of digital data to the DAC and the analog line output from the DAC. The default configuration of the **DAC/Line Outputs** tab is shown in Figure 26.



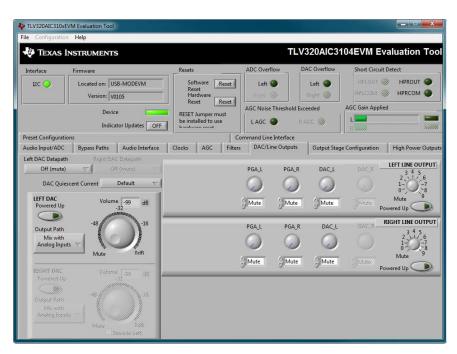


Figure 26. DAC/Line Outputs Tab

#### 4.10.1 **DAC Controls**

On the left side of this tab are controls for the DAC.

In similar fashion as the ADC, the DAC controls are set to allow control over the powering and volume setting of the DAC. The DAC volume level can be set by using the **Volume** knob.

The data from the audio serial interface used by the DAC is selected using the drop-down boxes under the DAC Datapath. The DAC channel can be selected to be off, use left channel data, use right channel data, or use a mono mix of the left and right data.

Analog audio coming from the DACs is routed to outputs using the Output Path controls in DAC control panel. The DAC output can be mixed with the analog inputs (PGA\_L, PGA\_R) and routed to the Line or High Power outputs using the mixer controls for these outputs on this tab (for the line outputs) or on the High Power Outputs tab (for the high power outputs). If the DAC is to be routed directly to either the Line or HP outputs, these can be selected as choices in the **Output Path** control. Note that if the Line or HP outputs are selected as the Output Path, the mixer controls on this tab and the High Power Output tabs have no effect.

#### 4.10.2 **Line Output Mixers**

On the right side of this tab are horizontal panels where the analog output mixing functions for the line outputs are located.

Each line output master volume is controlled by the knob at the far right of these panels, below the line output labels. The output amplifier gain can be muted or set at a value between 0 and 9 dB in 1-dB steps. Power/Enabled status for the line output can also be controlled using the button below this master output knob (Powered Up).

If the DAC **Output Path** control is set to *Mix with Analog Inputs*, the knobs in each panel can be used to set the individual level of signals routed and mixed to the line output. PGA L, PGA R, and DAC L levels can each be set to create a custom mix of signals presented to that particular line output.

NOTE: If the DAC Output Path control is set to anything other than Mix with Analog Inputs, these controls have no effect.



## 4.11 High-Power Outputs Tab



Figure 27. High-Power Outputs Tab

The High-Power Outputs tab contains horizontal groupings of controls, one for each one of the high power outputs. Each output has a mixer to mix the PGA\_L, PGA\_R, and DAC\_L signals, assuming that the DACs are not routed directly to the high power outputs. The High-Power Outputs tab is shown in Section 4.10.

At the left of each output strip is a **Powered Up** button that controls whether the corresponding output is powered up or not. The **When powered down** button allows the outputs to be tri-stated or driven weakly to the output common mode voltage.

The HPCOM output can be used as an independent output channel or can be used as a complementary signal to the HPOUT output. In these complementary configurations, the HPCOM output can be selected as *Differential of HPOUT* signal to the HPOUT output or may be set to be a common mode voltage (*Constant VCM Out*). When used in these configurations, the **Powered Up** button for the HPCOM output is disabled, as the power mode for that output will track the power status of the HPOUT output. The selection of *Differential of HPLCOM* or *Ext. Feedback/HPLCOM constant VCM* should not be selected for the TLV320AlC3109EVM evaluation.

At the right side of the output strip is a master volume knob for that output, which allows the output amplifier gain to be muted or set from 0 to 9 dB in 1-dB steps.

#### 4.12 Preset Configurations Tab

The Preset Configurations tab should be ignored for the evaluation of the TLV320AlC3109-Q1 as the configuration used in that tab is relevant for the TLV320AlC3104 device only. Scripts for the correct configuration of the TLV320AlC3109EVM are included in Appendix H. These scripts can be loaded into the EVM by using the **Command Line Interface** tab, shown in Figure 28.



#### 4.13 Command Line Interface Tab

A simple scripting language controls the TAS1020 on the USB-MODEVM from the LabVIEW<sup>TM</sup> based PC software. The main program controls, described previously, do nothing more than write a script which is then handed off to an interpreter that sends the appropriate data to the correct USB endpoint. Because this system is script-based, provision is made in this tab for the user to view the scripting commands created as the controls are manipulated, as well as load and execute other scripts that have been written and saved. The **Command Line Interface** tab is shown in Figure 28. This design allows the software to be used as a quick test tool or to help provide troubleshooting information in the rare event that the user encounters problem with this EVM.

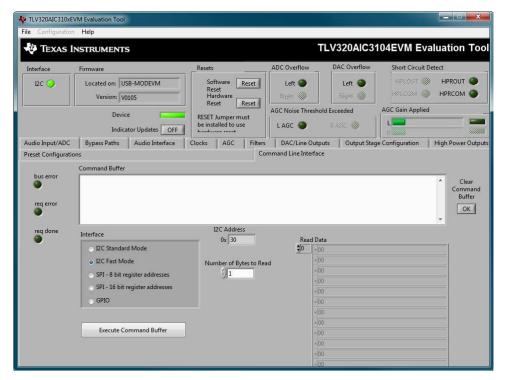


Figure 28. Command Line Interface Tab

A script is loaded into the command buffer, either by operating the controls on the other tabs or by loading a script file. When executed, the return packets of data which result from each command is displayed in the **Read Data** array control. When executing several commands, the Read Data control shows only the results of the last command. To see the results after every executed command, use the logging function described in the following paragraphs.

The **File** menu depicted in Figure 29 provides some options for working with scripts. The first option, *Open Command File...*, loads a command file script into the command buffer. This script can then be executed by pressing the **Execute Command Buffer** button.

The second option, Save Command File..., opens a save dialog box and then saves the text loaded in the **Command Buffer** into a text file defined by the user.

The third option is *Log Script and Results...*, which opens a file save dialog box. Choose a location for a log file to be written using this file save dialog. When the **Execute Command Buffer** button is pressed, the script runs and the script, along with resulting data read back during the script, will be saved to the file specified. The log file is a standard text file that can be opened with any text editor, and looks much like the source script file, but with the additional information of the result of each script command executed.



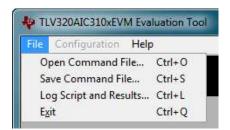


Figure 29. File Menu

Under the Help menu is an *About...* menu item which displays information about the TLV320AlC3109EVM software.

The actual USB protocol used as well as instructions on writing scripts are detailed in the following subsections. While it is not necessary to understand or use either the protocol or the scripts directly, understanding them may be helpful to some users.



# **EVM Connector Descriptions**

# A.1 Analog Interface Connectors

This appendix contains the connection details for each of the main header connectors on the EVM.

## A.1.1 Analog Dual-Row Header Details (J13 and J14)

For maximum flexibility, the TLV320AlC3109EVM is designed for easy interfacing to multiple analog sources. Table 6 summarizes the analog interface pinout for the TLV320AlC3109EVM.

**Table 6. Analog Interface Pinout** 

Pin Number	Signal	Description	
J1.1	NC	Not connected	
J1.2	NC	Not connected	
J1.3	HPCOM	High-power output driver (minus or multifunctional)	
J1.4	HPOUT	High-power output driver (plus)	
J1.5	LINE1M	MIC1 or LINE1 analog input (minus or multifunctional)	
J1.6	LINE1P	MIC1 or LINE1 analog input (plus or multifunctional)	
J1.7	LINE2M	MIC2 or LINE2 analog input (minus or multifunctional)	
J1.8	LINE2P	MIC2 or LINE2 analog input (plus or multifunctional)	
J1.9	AGND	Analog ground	
J1.10	NC	Not connected	
J1.11	AGND	Analog ground	
J1.12	NC	Not connected	
J1.13	AGND	Analog ground	
J1.14	MICBIAS	Microphone bias voltage output	
J1.15	NC	Not connected	
J1.16	MICDET	Microphone Detect	
J1.17	AGND	Analog ground	
J1.18	NC	Not connected	
J1.19	AGND	Analog ground	
J1.20	NC	Not connected	
J2.1	NC	Not connected	
J2.2	NC	Not connected	
J2.3	NC	Not connected	
J2.4	NC	Not connected	
J2.5	NC	Not connected	
J2.6	NC	Not connected	
J2.7	LEFT_LOP	Left-line output (plus)	
J2.8	LEFT_LOM	Left-line output (minus)	
J2.9	AGND	Analog ground	
J2.10	RIGHT_LOP	Right-line output (plus)	
J2.11	AGND	Analog ground	
J2.12	RIGHT_LOM	Right-line output (minus)	
J2.13	AGND	Analog ground	
J2.14	NC	Not connected	



**Table 6. Analog Interface Pinout (continued)** 

Pin Number	Signal	Description
J2.15	NC	Not connected
J2.16	NC	Not connected
J2.17	AGND	Analog ground
J2.18	NC	Not connected
J2.19	AGND	Analog ground
J2.20	NC	Not connected

## A.1.2 Analog Screw Terminal Details (J1-5 and J8-12)

In addition to the analog headers, the analog inputs and outputs can also be accessed through alternate connectors, either screw terminals or audio jacks. The mono microphone is also tied to J13 and the mono headphone output is available at J16.

Table 7 summarizes the screw terminals available on the TLV320AlC3109EVM.

**Table 7. Alternate Analog Connectors** 

Designator Pin 1		Pin 2	Pin 3
J6	External mic bias source (+)	External mic bias source (GND)	
J10	10 LINE2 (+) LINE2 (-)		AGND
J13	LINE1 (+)	LINE1 (-)	AGND
J17	AGND	HPCOM (-)	HPOUT (+)
J20	LEFT OUT (+)	LEFT OUT (-)	
J21	RIGHT OUT (+)	RIGHT OUT (-)	



# A.2 Digital Interface Connectors (J16 and J17)

The TLV320AlC3109EVM is designed to easily interface with multiple control platforms. Table 8 summarizes the digital interface pinout for the TLV320AlC3109EVM.

**Table 8. Digital Interface Pinout** 

Pin Number	Signal	Description	
J4.1	NC	Not connected	
J4.2	NC	Not connected	
J4.3	SCLK	SPI serial clock	
J4.4	DGND	Digital ground	
J4.5	NC	Not connected	
J4.6	NC	Not connected	
J4.7	NC	Not connected	
J4.8	RESET INPUT	Reset signal input to EVM	
J4.9	NC	Not connected	
J4.10	DGND	Digital ground	
J4.11	NC	Not connected	
J4.12	NC	Not connected	
J4.13	NC	Not connected	
J4.14	RESET	Reset	
J4.15	NC	Not connected	
J4.16	SCL	I <sup>2</sup> C serial clock	
J4.17	NC	Not connected	
J4.18	DGND	Digital ground	
J4.19	NC	Not connected	
J4.20	SDA	I <sup>2</sup> C serial data I/O	
J5.1	NC	Not connected	
J5.2	NC	Not connected	
J5.3	BCLK	Audio serial data bus bit clock (I/O)	
J5.4	DGND	Digital ground	
J5.5	NC	Not connected	
J5.6	NC	Not connected	
J5.7	WCLK	Audio serial data bus word clock (I/O)	
J5.8	NC	Not connected	
J5.9	NC	Not connected	
J5.10	DGND	Digital ground	
J5.11	DIN	Audio serial data bus data input (input)	
J5.12	NC	Not connected	
J5.13	DOUT	Audio serial data bus data output (output)	
J5.14	NC	Not connected	
J5.15	NC	Not connected	
J5.16	SCL	I <sup>2</sup> C serial clock	
J5.17	MCLK	Master clock input	
J5.18	DGND	Digital ground	
J5.19	NC	Not connected	
J5.20	SDA	I <sup>2</sup> C Serial Data I/O	



Note that J5 comprises the signals needed for an I<sup>2</sup>S serial digital audio interface; the control interface (I<sup>2</sup>C and RESET) signals are routed to J4. I<sup>2</sup>C is actually routed to both connectors; however, the device is connected only to J4.

# A.3 Power Supply Connector Pin Header, J3

J3 provides connection to the common power bus for the TLV320AlC3109EVM. Power is supplied on the pins listed in Table 9.

**Table 9. Power Supply Pinout** 

Signal	Pin Number		Signal
NC	J3.1	J3.2	NC
+5VA	J3.3	J3.4	NC
DGND	J3.5	J3.6	AGND
+1.8VD	J3.7	J3.8	NC
+3.3VD	J3.9	J3.10	NC

The TLV320AlC3109EVM motherboard (the USB-MODEVM Interface board) supplies power to J3 of the TLV320AlC3109EVM. Power for the motherboard is supplied either through its USB connection or via terminal blocks on that board.



# TLV320AIC3109EVM Schematic

### B.1 Main Schematics

Figure 30 illustrates the main TLV320AlC3109-Q1 schematics.

### TLV320AIC3109EVMDC006 Rev A

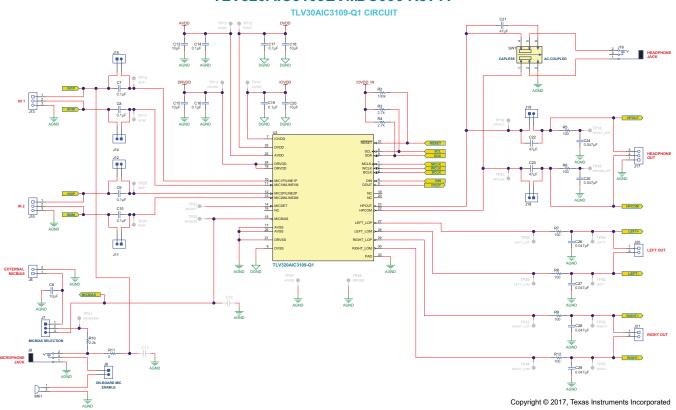


Figure 30. TLV320AlC3109-Q1 Main Schematics



Secondary Schematics www.ti.com

# **B.2** Secondary Schematics

Figure 31 illustrates the secondary TLV320AlC3109-Q1 schematics.

# TLV320AIC3109EVMDC006 Rev A

**Secondary Circuits** 

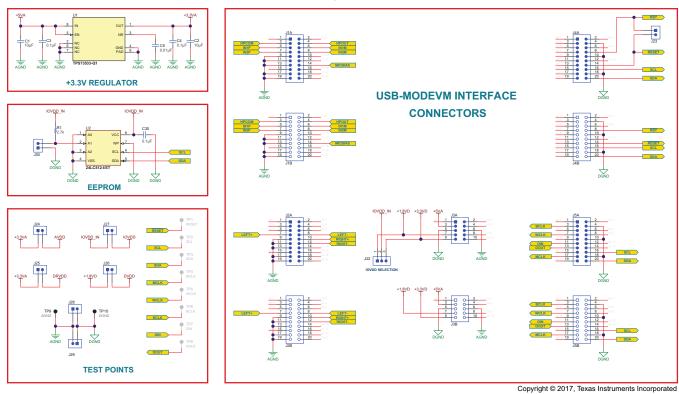


Figure 31. Connector, Test Points, and Power Distribution Schematics



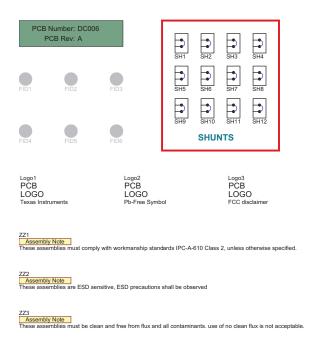
www.ti.com Hardware Schematics

### **B.3** Hardware Schematics

Figure 32 illustrates the TLV320AlC3109-Q1 hardware.

# TLV320AlC3109-Q1 Evaluation Module DC006 RevA

**HARDWARE** 



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Figure 32. TLV320AIC3109EVM Hardware



# TLV320AIC3109EVM Layout Views

The board layouts for the modular TLV320AlC3109EVM are illustrated in Figure 33 through Figure 38.

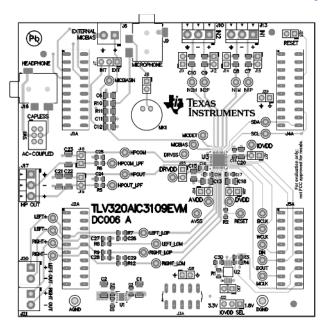


Figure 33. TLV320AIC3109EVM Assembly Layer

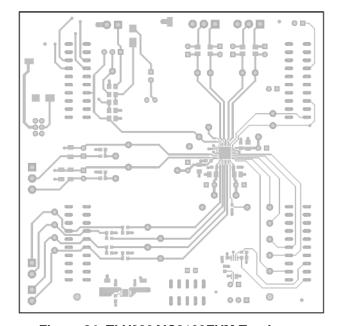


Figure 34. TLV320AIC3109EVM Top Layer



www.ti.com Appendix C

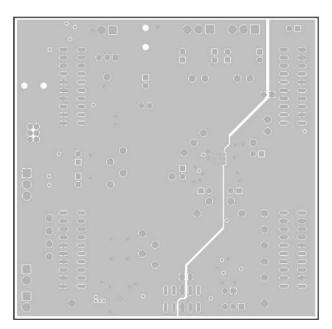


Figure 35. TLV320AIC3109EVM Ground Layer

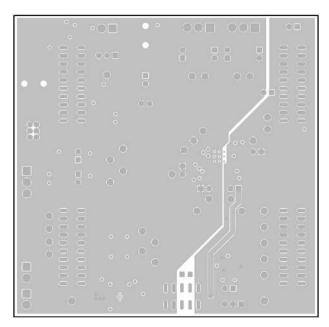


Figure 36. TLV320AlC3109EVM Power Layer



Appendix C www.ti.com

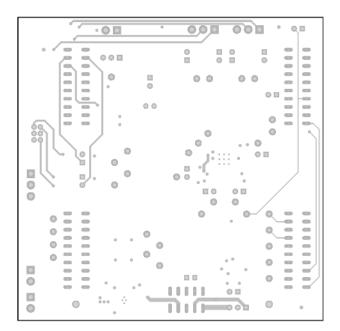


Figure 37. TLV320AIC3109EVM Bottom Layer

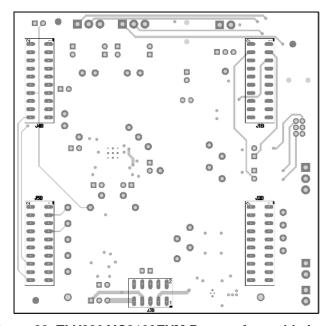


Figure 38. TLV320AIC3109EVM Bottom Assembly Layer



# TLV320AIC3109EVM Bill of Materials

The complete bill of materials for the modular TLV320AlC3109EVM is provided in Table 10.

# Table 10. TLV320AIC3109EVM Bill of Materials

#	Designator	Qty	Value	Part Number	Manufacturer	Description	Package Reference
1	!PCB101	1		DC006	Any	Printed Circuit Board	
2	C1, C2	2	10uF	C3216X5R1H106K160AB	TDK	CAP, CERM, 10 μF, 50 V, ±±10%, X5R, 1206	
3	C3, C4, C14, C16, C17, C19, C30	7	0.1uF	C1608X7R1H104K080AA	TDK	CAP, CERM, 0.1 μF, 50 V, ±10%, X7R, 0603	0603
4	C5	1	0.01uF	GRM188R71C103KA01D	Murata	CAP, CERM, 0.01 μF, 16 V, ±10%, X7R, 0603	0603
5	C6, C13, C15, C18, C20	5	10uF	C2012X5R1E106K125AB	TDK	CAP, CERM, 10 μF, 25 V, ±10%, X5R, 0805	0805
6	C7, C8, C9, C10	4	0.1uF	C2012X7R1H104K085AA	TDK	CAP, CERM, 0.1 μF, 50 V, ±10%, X7R, 0805	0805
7	C21, C22, C23	3	47uF	C3216X5R1C476M160AB	TDK	CAP, CERM, 47 μF, 16 V, ±15%, X5R, 1206	1206
8	C24, C25, C26, C27, C28, C29	6	0.047uF	C1608X7R1H473K080AA	TDK	CAP, CERM, 0.047 μF, 50 V, ±10%, X7R, 0603	0603
9	J1A, J2A, J4A, J5A	4		TSM-110-01-L-DV-P	Samtec	Header, 2.54mm, 10x2, Gold, SMT	1000x180x290mil
10	J1B, J2B, J4B, J5B	4		SSW-110-22-F-D-VS-K	Samtec	Connector, Receptacle, 100mil, 10x2, Gold plated, SMD	10x2 Receptacle
11	J3A	1		TSM-105-01-L-DV	Samtec	Header, 2.54mm, 5x2, Gold, SMT	Header, 2.54mm, 5x2, SMT
12	J3B	1		SSW-105-22-F-D-VS-K	Samtec	Connector, Header, 10-Pos (5x2), Receptacle, 100x100-mil Pitch	5x2 Receptacle
13	J6, J20, J21	3		ED555/2DS	On-Shore Technology	Terminal Block, 3.5mm Pitch, 2x1, TH	7.0x8.2x6.5mm
14	J7, J22	2		TSW-103-07-G-S	Samtec	Header, 100mil, 3x1, Gold, TH	3x1 Header
15	J8, J11, J12, J14, J15, J18, J19, J23, J24, J25, J26, J27, J28, J29, J30	15		TSW-102-07-G-S	Samtec	Header, 100mil, 2x1, Gold, TH	2x1 Header
16	J9, J16	2		MJ1-3510-SMT-TR	CUI Inc.	Audio Jack, 3.5mm, Mono, R/A, Black, SMT	Audio Jack, 3.5mm, Mono, R/A, Black, SMT
17	J10, J13, J17	3		ED555/3DS	On-Shore Technology	Terminal Block, 3.5mm Pitch, 3x1, TH	10.5x8.2x6.5mm
18	MK1	1		CMA-4544PF-W	CUI Inc.	Microphone, Electret Condenser, Omnidirectional, -44 dB, TH	THD, 2-Leads, Dia 9.85mm, Pin Spacing 2.54mm
19	R1, R3, R4	3	2.7k	CRCW06032K70JNEA	Vishay-Dale	RES, 2.7 k, 5%, 0.1 W, 0603	0603
20	R2	1	100k	RC0603FR-07100KL	Yageo America	RES, 100 k, 1%, 0.1 W, 0603	0603
21	R5, R6, R7, R8, R9, R12	6	100	RC0603FR-07100RL	Yageo America	RES, 100, 1%, 0.1 W, 0603	0603
22	R10	1	2.2k	CRCW08052K20JNEA	Vishay-Dale	RES, 2.2 k, 5%, 0.125 W, 0805	0805
23	R11	1	0	CRCW08050000Z0EA	Vishay-Dale	RES, 0, 5%, 0.125 W, 0805	0805
24	SH1, SH2, SH3, SH4, SH5, SH6, SH7, SH8, SH9, SH10, SH11, SH12	12	1x2	SNT-100-BK-G	Samtec	Shunt, 100mil, Gold plated, Black	Shunt
25	SW1	1		SSB22	TE Connectivity	Switch, Slide, DPDT, On-On, 0.1 A, 30 V, TH TH, 6-Leads 9.25x5.65m 2mm	
26	TP9, TP10	2	-	5011	Keystone	Test Point, Multipurpose, Black, TH Black Multip Testpoint	
27	U1	1		TPS73533-Q1	Texas Instruments	500-mA, Low Quiescent Current, Low-Noise, High PSRR, Low-Dropout Linear Regulator for Automotive, DRB0008B (VSON-8)	DRB0008B
28	U2	1		24LC512-I/ST	Microchip	EEPROM, 512KBIT, 400KHZ, 8TSSOP	TSSOP-8



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# Table 10. TLV320AIC3109EVM Bill of Materials (continued)

#	Designator	Qty	Value	Part Number	Manufacturer	Description	Package Reference
29	U3	1		TLV320AlC3109-Q1	Texas Instruments	Low-Power Mono Audio Codec for Automotive RHB0032E Applications, RHB0032E (VQFN-32)	
30	C11, C12	0	0.1uF	C2012X7R1H104K085AA	TDK	CAP, CERM, 0.1 μF, 50 V, ±10%, X7R, 0805	0805
31	FID1, FID2, FID3, FID4, FID5, FID6	0		N/A	N/A	Fiducial mark. There is nothing to buy or mount.	Fiducial
32	TP1, TP2, TP3, TP4, TP5, TP6, TP7, TP8, TP11, TP12, TP13, TP14, TP15, TP16, TP17, TP18, TP19, TP20, TP21, TP22, TP23, TP24, TP25, TP26, TP27, TP28, TP29, TP30, TP31, TP32, TP33, TP34, TP35	0		5000	Keystone	Test Point, Miniature, Red, TH	Red Miniature Testpoint



# **USB-MODEVM Schematic**

The schematic diagrams for the USB-MODEVM Interface Board (included only in the TLV320AlC3109EVM-K) are illustrated in Figure 39 and Figure 40.

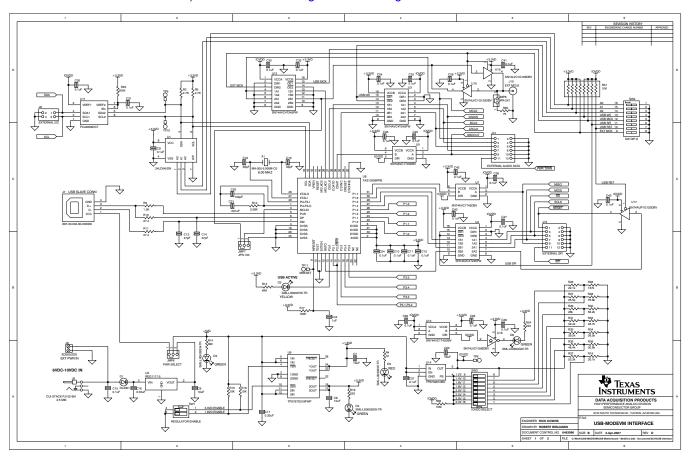


Figure 39. USB-MODEVM Interface Board Schematic (1 of 2)



Appendix E www.ti.com

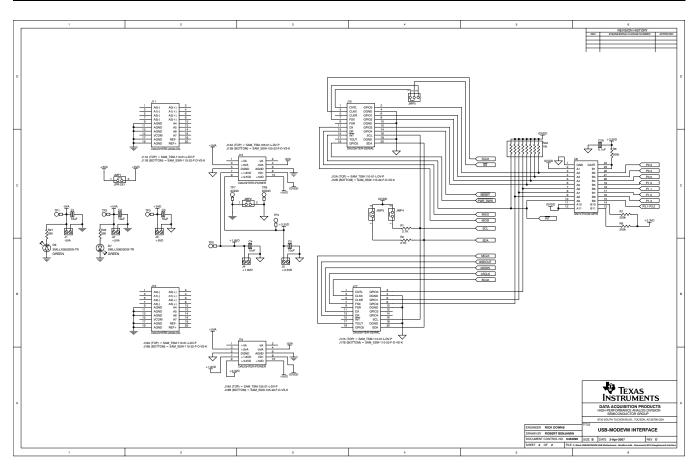


Figure 40. USB-MODEVM Interface Board Schematic (2 of 2)



# **USB-MODEVM Layout Views**

The USB-MODEVM interface board layouts (included only in the TLV320AlC3109EVM-K) are illustrated in Figure 41 through Figure 43.

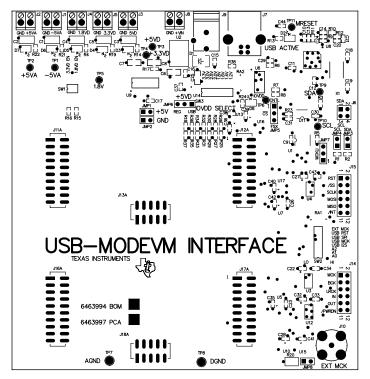


Figure 41. USB-MODEVM Assembly Layer



Appendix F www.ti.com

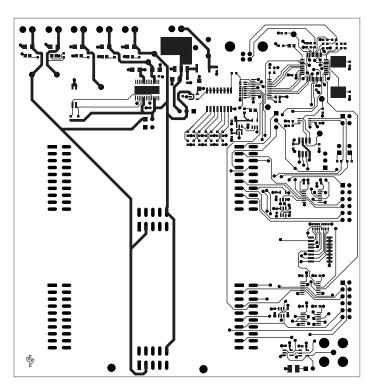


Figure 42. USB-MODEVM Top Layer

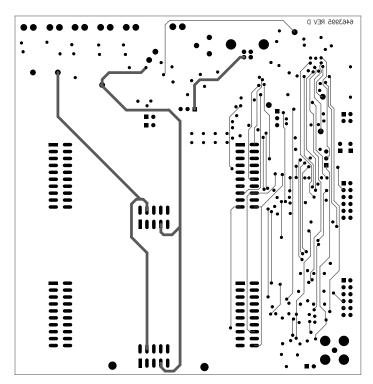


Figure 43. USB-MODEVM Bottom Layer



# **USB-MODEVM Bill of Materials**

The complete bill of materials for the USB-MODEVM Interface Board (included only in the TLV320AIC3109EVM) is provided in Table 11.

Table 11. USB-MODEVM Bill of Materials

Designators	Description	Manufacturer	Mfr Part Number		
R4	10Ω 1/10W 5% Chip Resistor	Panasonic	ERJ-3GEYJ1300V		
R10, R11	27.4Ω 1/16W 1% Chip Resistor	Panasonic	ERJ-3EKF27R4V		
R20	75Ω 1/4W 1% Chip Resistor	Panasonic	ERJ-14NF75R0U		
R19	220Ω 1/10W 5% Chip Resistor	Panasonic	ERJ-3GEYJ221V		
R14, R21, R22	390Ω 1/10W 5% Chip Resistor	Panasonic	ERJ-3GEYJ391V		
R13	649Ω 1/16W 1% Chip Resistor	Panasonic	ERJ-3EKF6490V		
R9	1.5KΩ 1/10W 5% Chip Resistor	Panasonic	ERJ-3GEYJ1352V		
R1–R3, R5–R8	2.7KΩ 1/10W 5% Chip Resistor	Panasonic	ERJ-3GEYJ272V		
R12	3.09KΩ 1/16W 1% Chip Resistor	Panasonic	ERJ-3EKF3091V		
R15, R16	10KΩ 1/10W 5% Chip Resistor	Panasonic	ERJ-3GEYJ1303V		
R17, R18	100kΩ 1/10W 5%Chip Resistor	Panasonic	ERJ-3GEYJ1304V		
RA1	10KΩ 1/8W Octal Isolated Resistor Array	CTS Corporation	742C163103JTR		
C18, C19	33pF 50V Ceramic Chip Capacitor, ±5%, NPO	TDK	C1608C0G1H330J		
C13, C14	47pF 50V Ceramic Chip Capacitor, ±5%, NPO	TDK	C1608C0G1H470J		
C20	100pF 50V Ceramic Chip Capacitor, ±5%, NPO	TDK	C1608C0G1H101J		
C21	1000pF 50V Ceramic Chip Capacitor, ±5%, NPO	TDK	C1608C0G1H102J		
C15	0.1μF 16V Ceramic Chip Capacitor, ±10%, X7R	TDK	C1608X7R1C104K		
C16, C17	0.33μF 16V Ceramic Chip Capacitor, ±20%, Y5V	TDK	C1608X5R1C334K		
C9-C12, C22-C28	1μF 6.3V Ceramic Chip Capacitor, ±10%, X5R	TDK	C1608X5R0J1305K		
C1–C8	10μF 6.3V Ceramic Chip Capacitor, ±10%, X5R	TDK	C3216X5R0J1306K		
D1	50V, 1A, Diode MELF SMD	Micro Commercial Components	DL4001		
D2	Yellow Light Emitting Diode	Lumex	SML-LX0603YW-TR		
D3- D7	Green Light Emitting Diode	Lumex	SML-LX0603GW-TR		
D5	Red Light Emitting Diode	Lumex	SML-LX0603IW-TR		
Q1, Q2	N-Channel MOSFET	Zetex	ZXMN6A07F		
X1	6MHz Crystal SMD	Epson	MA-505 6.000M-C0		
U8	USB Streaming Controller	Texas Instruments	TAS1020BPFB		
J2	5V LDO Regulator	Texas Instruments	REG1117-5		
J9	3.3V/1.8V Dual Output LDO Regulator	Texas Instruments	TPS767D318PWP		
J3, U4	Quad, 3-State Buffers	Texas Instruments	SN74LVC125APW		
U5–U7	Single IC Buffer Driver with Open Drain o/p	Texas Instruments	SN74LVC1G07DBVR		
J10	Single 3-State Buffer	Texas Instruments	SN74LVC1G125DBVR		
J1	64K 2-Wire Serial EEPROM I <sup>2</sup> C	Microchip	24LC64I/SN		
	USB-MODEVM PCB	Texas Instruments	6463995		
ГР1–ТР6, ТР9–ТР11	Miniature test point terminal	Keystone Electronics	5000		
TP7, TP8 Multipurpose test point terminal		Keystone Electronics	5011		
J7	USB Type B Slave Connector Thru-Hole	Mill-Max	897-30-004-90-000000		
J13, J2–J5, J8	2-position terminal block	On Shore Technology	ED555/2DS		
J9	2.5mm power connector	CUI Stack	PJ-102B		
	•		1		



Appendix G www.ti.com

# Table 11. USB-MODEVM Bill of Materials (continued)

Designators	Description	Manufacturer	Mfr Part Number	
J130	BNC connector, female, PC mount	AMP/Tyco	414305-1	
J131A, J132A, J21A, J22A 20-pin SMT plug		Samtec	TSM-110-01-L-DV-P	
J131B, J132B, J21B, J22B	20-pin SMT socket	Samtec	SSW-110-22-F-D-VS-K	
J133A, J23A	10-pin SMT plug	Samtec	TSM-105-01-L-DV-P	
J133B, J23B	10-pin SMT socket	Samtec	SSW-105-22-F-D-VS-K	
J6 4-pin double row header (2x2) 0.1"		Samtec	TSW-102-07-L-D	
J134, J135 12-pin double row header (2x6) 0.1"		Samtec	TSW-106-07-L-D	
JMP1–JMP4 2-position jumper, 0.1" spacing		Samtec	TSW-102-07-L-S	
JMP8–JMP14 2-position jumper, 0.1" spacing		Samtec	TSW-102-07-L-S	
JMP5, JMP6	3-position jumper, 0.1" spacing	Samtec	TSW-103-07-L-S	
JMP7 3-position dual row jumper, 0.1" spacing		Samtec	TSW-103-07-L-D	
SW1 SMT, half-pitch 2-position switch		C&K Division, ITT	TDA02H0SK1	
SW2	SMT, half-pitch 8-position switch	C&K Division, ITT	TDA08H0SK1	
	Jumper plug	Samtec	SNT-100-BK-T	



# TLV320AIC3109-Q1 Configuration Scripts

This appendix contains configuration scripts used for the TLV320AlC3109-Q1 device.

## H.1 DAC: Mono Playback to AC coupled Headphone output

```
Mono Playback to AC coupled Headphone output
# Switch SW1 on AC-COUPLED position
# DAC connected to headphone output through mixer path
# Mixer Gain = OdB; Output amplifier gain = OdB
# AC coupled headphone configuration
\# I2S, 16-bits, fs = 44.1KHz
# MCLK = 11.2896MHz; BCLK = 2.8224MHz; WCLK = 44.1KHz
# Page 0 selected
w 30 00 00
# Software Reset
w 30 01 80
# fs(ref) setting and DAC data
w 30 07 8A
# DAC unmuted, OdB gain
w 30 2B 00
# AC-coupling output
w 30 OE CO
# DAC powered up
# HPCOM as independent single-ended output
w 30 26 10
# DAC routed to HPOUT output
w 30 3D 80
\mbox{\tt\#} HPOUT output powered up, 0dB
w 30 41 0D
# DAC reference current 100%
w 30 6D C0
```



# H.2 DAC: Mono Playback to Capless Headphone output

```
Mono Playback to Capless Headphone output
# Switch SW1 on CAPLESS position
# DAC connected to headphone output through mixer path
# Mixer Gain = OdB; Output amplifier gain = OdB
# Capless headphone configuration
\# I2S, 16-bits, fs = 44.1KHz
# MCLK = 11.2896MHz; BCLK = 2.8224MHz; WCLK = 44.1KHz
# Page 0 selected
w 30 00 00
# Software Reset
w 30 01 80
# fs(ref) setting and DAC data
w 30 07 8A
# DAC unmuted, OdB gain
w 30 2B 00
# AC-coupling output
w 30 0E C0
# DAC powered up
w 30 25 80
\# HPCOM VCM output voltage = 1.35V
w 30 28 00
# HPCOM as constant VCM output
w 30 26 08
# DAC routed to HPOUT output
w 30 3D 80
# HPOUT output powered up, 0dB
w 30 41 0D
# DAC reference current 100%
w 30 6D C0
```



### H.3 DAC: Mono Playback to Line output

```
Mono Playback to Line output
# DAC connected to line output through mixer path
# Mixer Gain = 0dB; Output amplifier gain = 0dB
\# I2S, 16-bits, fs = 44.1KHz
# MCLK = 11.2896MHz; BCLK = 2.8224MHz; WCLK = 44.1KHz
# Page 0 selected
w 30 00 00
# Software Reset
w 30 01 80
# fs(ref) setting and DAC data
w 30 07 8A
# DAC unmuted, OdB gain
w 30 2B 00
# DAC powered up
w 30 25 80
# DAC routed to LEFT_LOP output
w 30 52 80
# LEFT_LOP output powered up, 0dB
w 30 56 0D
# DAC routed to RIGHT_LOP output
w 30 59 80
# RIGHT_LOP output powered up, 0dB
w 30 5D 0D
# DAC reference current 100%
w 30 6D C0
```



# H.4 ADC: On-board microphone to digital audio output

```
On-board microphone to digital output
# Jumpers J7 and J8 in default position
# On-board Microphone connected to the ADC block
# PGA = 0dB; ADC volume = 0dB
# MICBIAS level = 2.5V
\# I2S, 16-bits, fs = 44.1KHz
# MCLK = 11.2896MHz; BCLK = 2.8224MHz; WCLK = 44.1KHz
# Page 0 selected
w 30 00 00
# Software Reset
w 30 01 80
# fs(ref) setting
w 30 07 80
\# High-pass filter selected, fc = 0x0045 * ADC_fs
w 30 OC 40
\# MICBIAS = 2.5V
w 30 19 80
# IN1P routed to ADC (0dB); ADC powered up
w 30 13 04
# PGA unmuted, OdB
w 30 Of 00
```



### H.5 ADC: Differential input to digital audio output

```
Differential input to digital output
# IN1P/IN1M input selected
# On-board Microphone connected to the ADC block
# PGA = 0dB; ADC volume = 0dB
\# I2S, 16-bits, fs = 44.1KHz
# MCLK = 11.2896MHz; BCLK = 2.8224MHz; WCLK = 44.1KHz
# Page 0 selected
w 30 00 00
# Software Reset
w 30 01 80
# fs(ref) setting
w 30 07 80
\# High-pass filter selected, fc = 0x0045 * ADC_fs
w 30 OC 40
# IN1P routed to ADC (0dB); ADC powered up
w 30 13 84
# PGA unmuted, OdB
w 30 Of 00
```



# **USB-MODEVM Protocol**

### I.1 USB-MODEVM Protocol

The USB-MODEVM is defined to be a *Vendor-Specific* class, and is identified on the PC system as an NI-VISA device. Because the TAS1020 has several routines in its ROM which are designed for use with HID-class devices, HID-like structures are used, even though the USB-MODEVM is not an HID-class device. Data is passed from the PC to the TAS1020 using the control endpoint.

Data is sent in an HIDSETREPORT (see Table 12):

Table 12. USB Control Endpoint HIDSETREPORT Request

Part	Value	Description		
bmRequestType	0x21	00100001		
bRequest	0x09	SET_REPORT		
wValue	0x00	don't care		
wIndex	0x03	HID interface is index 3		
wLength	calculated by host			
Data		Data packet as described in Table 13.		

The data packet consists of the following bytes, shown in Table 13 and the following paragraphs:

**Table 13. Data Packet Configuration** 

Byte Number	Туре	Description				
0	Interface	Specifies serial interface and operation. The two values are logically ORed. Operation:				
		READ 0x00 WRITE 0x10				
		Interface:				
		GPIO 0x08 SPI_16 0x04 I2C_FAST 0x02 I2C_STD 0x01 SPI_8 0x00				
1	I <sup>2</sup> C Slave Address	Slave address of I <sup>2</sup> C device or MSB of 16-bit reg addr for SPI				
2	Length	Length of data to write/read (number of bytes)				
3	Register address	Address of register for I <sup>2</sup> C or 8-bit SPI; LSB of 16-bit address for SPI				
464	Data	Up to 60 data bytes could be written at a time. EP0 maximum length is 64. The return packet is limited to 42 bytes, so advise only sending 32 bytes at any one time.				



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#### Example usage:

Write two bytes (AA, 55) to device starting at register 5 of an I<sup>2</sup>C device with address A0:

- [0] 0x11
- [1] 0xA0
- [2] 0x02
- [3] 0x05
- [4] 0xAA
- [5] 0x55

Do the same with a fast mode I<sup>2</sup>C device:

- [0] 0x12
- [1] 0xA0
- [2] 0x02
- [3] 0x05
- [4] 0xAA
- [5] 0x55

Now with an SPI device which uses an 8-bit register address:

- [0] 0x10
- [1] 0xA0
- [2] 0x02
- [3] 0x05
- [4] 0xAA
- [5] 0x55

A 16-bit register address, as found on parts like the TSC2101. Assume the register address (command word) is **0x10E0**:

- [0] 0x14
- [1]  $0 \times 10$  --> **Note:** the I<sup>2</sup>C address now serves as MSB of reg addr.
- [21 0x02
- [3] 0xE0
- [4] 0xAA
- [5] 0x55

In each case, the TAS1020 will return, in an HID interrupt packet, the following:

[0] interface byte | status

#### status:

REQ\_ERROR 0x80 INTF\_ERROR 0x40 REQ\_DONE 0x20

- [1] for I<sup>2</sup>C interfaces, the I<sup>2</sup>C address as sent
  - for SPI interfaces, the read back data from SPI line for transmission of the corresponding byte
- [2] length as sent
- [3] for I<sup>2</sup>C interfaces, the reg address as sent

for SPI interfaces, the read back data from SPI line for transmission of the corresponding byte

[4..60] echo of data packet sent



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If the command is sent with no problem, the returning byte [0] should be the same as the sent one logically ORed with 0x20 - in the first example, the returning packet should be:

- [0] 0x31 [1] 0xA0 [2] 0x02 [3] 0x05
- [4] 0xAA [5] 0x55

If for some reason the interface fails (for example, the I2C device does not acknowledge), it would come back as:

- [0] 0x51 --> interface | INTF\_ERROR [1] 0xA0
- [2] 0x02
- [3] 0x05
- [4] 0xAA
- [5] 0x55

If the request is malformed, that is, the interface byte (byte [0]) takes on a value which is not previously described, the return packet would be:

- [0] 0x93 --> the user sent 0x13, which is not valid, so 0x93 returned
- [1] 0xA0
- [2] 0x02
- [3] 0x05
- [4] 0xAA
- [5] 0x55

The previous examples used writes. Reading is similar:

Read two bytes from device starting at register 5 of an I<sup>2</sup>C device with address A0:

- [0] 0x01
- [1] 0xA0
- [2] 0x02
- [3] 0x05



www.ti.com GPIO Capability

### The return packet should be

- [0] 0x21
- [1] 0xA0
- [2] 0x02
- [3] 0x05
- [4] 0xAA
- [5] 0x55

assuming that the values previously written starting at Register 5 were actually written to the device.

# I.2 GPIO Capability

The USB-MODEVM has seven GPIO lines. Access them by specifying the interface to be 0x08, and then using the standard format for packets—but addresses are unnecessary. The GPIO lines are mapped into one byte (see Table 14):

#### Table 14. GPIO Pin Assignments

Bit 7	6	5	4	3	2	1	0
Х	P3.5	P3.4	P3.3	P1.3	P1.2	P1.1	P1.0

Example: write P3.5 to a 1, set all others to 0:

- [0] 0x18 --> write, GPIO
- [1] 0x00 --> this value is ignored
- [2] 0x01 --> length ALWAYS a 1
- [3] 0x00 --> this value is ignored
- [4] 0x40 --> 01000000

The user may also read back from the GPIO to see the state of the pins. Consider if the previous example was written to the port pins.

## Example: read the GPIO

- [0] 0x08 --> read, GPIO
- [1] 0x00 --> this value is ignored
- [2] 0x01 --> length ALWAYS a 1
- [3] 0x00 --> this value is ignored

#### The return packet should be:

- [0] 0x28
- [1] 0x00
- [2] 0x01
- [3] 0x00
- [4] 0x40

### I.3 Writing Scripts

A script is simply a text file that contains data to send to the serial control buses. The scripting language is quite simple, as is the parser for the language. Therefore, the program is not very forgiving about mistakes made in the source script file, but the formatting of the file is simple. Consequently, mistakes should be rare.



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Each line in a script file is one command. There is no provision for extending lines beyond one line. A line is terminated by a carriage return.

The first character of a line is the command. Commands are:

- Set interface bus to use
- Read from the serial control bus
- Write to the serial control bus
- Comment
- b Break
- d Delay

The first command, I, sets the interface to use for the commands to follow. This command must be followed by one of the following parameters:

i2cstd	Standard mode I <sup>2</sup> C Bus
i2cfast	Fast mode I <sup>2</sup> C bus

SPI bus with 8-bit register addressing spi8 SPI bus with 16-bit register addressing spi16 apio Use the USB-MODEVM GPIO capability

For example, if a fast mode I<sup>2</sup>C bus is to be used, the script begins with:

No data follows the break command. Anything following a comment command is ignored by the parser, provided that it is on the same line. The delay command allows the user to specify a time, in milliseconds, that the script will pause before proceeding.

NOTE: Unlike all other numbers used in the script commands, the delay time is entered in a decimal format. Also, note that because of latency in the USB bus as well as the time it takes the processor on the USB-MODEVM to handle requests, the delay time may not be precise.

A series of byte values follows either a read or write command. Each byte value is expressed in hexadecimal, and each byte must be separated by a space. Commands are interpreted and sent to the TAS1020 by the program using the protocol described in Section I.1.

The first byte following a read or write command is the I<sup>2</sup>C slave address of the device (if I<sup>2</sup>C is used) or the first data byte to write (if SPI is used—note that SPI interfaces are not standardized on protocols, so the meaning of this byte will vary with the device being addressed on the SPI bus). The second byte is the starting register address that data will be written to (again, with I<sup>2</sup>C; SPI varies—see Section I.1 for additional information about what variations may be necessary for a particular SPI mode). Following these two bytes are data, if writing; if reading, the third byte value is the number of bytes to read, (expressed in hexadecimal).

For example, to write the values 0xAA 0x55 to an I<sup>2</sup>C device with a slave address of 0x90, starting at a register address of 0x03, one would write:

```
#example script
I i2cfast
w 90 03 AA 55
r 90 03 2
```

This script begins with a comment, specifies that a fast I2C bus will be used, then writes 0xAA 0x55 to the I<sup>2</sup>C slave device at address 0x90, writing the values into registers 0x03 and 0x04. The script then reads back two bytes from the same device starting at register address 0x03. Note that the slave device value does not change. It is not necessary to set the R/W bit for I2C devices in the script; the read or write commands will do that.



www.ti.com Writing Scripts

Here is an example of using an SPI device that requires 16-bit register addresses:

Note that blank lines are allowed. However, be sure that the script does not end with a blank line. While ending with a blank line will not cause the script to fail, the program will execute that line, and therefore, may prevent the user from seeing data that was written or read back on the previous command.

In this example, the first two bytes of each command are the command word to send to the TSC2101 (0x1000, 0x1360); these are followed by data to write to the device starting at the address specified in the command word. The second line may wrap in the viewer being used to look like more than one line; careful examination will show; however, that there is only one carriage return on that line, following the last **no** 

Any text editor may be used to write these scripts; Jedit is an editor that is highly recommended for general usage. For more information, go to: http://www.jedit.org.

Once the script is written, it can be used in the command window by running the program, and then selecting *Open Command File...* from the File menu. Locate the script and open it. The script will then be displayed in the command buffer. The user may also edit the script once it is in the buffer, but saving of the command buffer is not possible at this time (this feature may be added at a later date).

Once the script is in the command buffer, it may be executed by pressing the *Execute Command Buffer* button. If there are breakpoints in the script, the script will execute to that point, and the user is presented with a dialog box with a button to press to continue executing the script. When ready to proceed, push that button and the script will continue.

Here an example of a (partial) script with breakpoints:

This script writes the value 8A at register 7, then reads it back to verify that the write was good. A delay of 1000 ms (one second) is placed after the read to pause the script operation. When the script continues, the values **00 00** are written starting at register 0F. This output is verified by reading two bytes, and pausing the script again, this time with a break. The script does not continue until the user allows it to by pressing *OK* in the dialog box that is displayed due to the break.

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- · Reorient or relocate the receiving antenna.
- Increase the separation between the equipment and receiver.
- · Connect the equipment into an outlet on a circuit different from that to which the receiver is connected.
- Consult the dealer or an experienced radio/TV technician for help.

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3.2.1 For EVMs issued with an Industry Canada Certificate of Conformance to RSS-210 or RSS-247

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